

IN THE SPECIFICATION

Please replace the following corresponding numbered paragraph of the specification. Applicants include herewith a marked up version of the replacement paragraph, marked with underlines to indicate any insertions and strikethroughs to indicate any deletions.

[0006] The object of an embodiment of the present invention is to specify a method and a device with which printed circuit boards with coarse and fine conductor structures can be patterned in as simple and economical way as possible. According to an embodiment of the invention, this object can be achieved with the following method steps:

- a) applying a metal layer to an electrically insulating substrate,
- b) applying an etch resist layer to the metal layer,
- c) exposing the contours (62) of the envisaged coarse conductor structures (31) by partially eroding the etch resist layer (61) with a first laser beam (14) with a predefined first wavelength and a first processing field size (3) which is predefined by a first imaging unit (13),
- d) exposing the contours (63) of the fine conductor structures by partially eroding the etch resist layer (61) with a second laser beam (24) with a predefined second wavelength and a second processing field size (4) which is predefined by a second imaging unit (23), the second wavelength being shorter than the first wavelength and/or the second field size (4) being smaller than the first field size (3),
- e) producing the coarse and the fine conductor structures (31, 41) simultaneously by etching the exposed metal regions (62, ~~67~~ 63), and
- f) exposing the surfaces of the conductor structures by eroding the rest of the etch resist layer.